FAIRCHILD SEMICONDUCTOR™

April 2001
Revised June 2003

FIN1027 • FIN1027A
3.3V LVDS 2-Bit High Speed Differential Driver

General Description

This dual driver is designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTL signal levels to LVDS levels with a typical differential output swing of 350 mV which provides low EMI at ultra low power dissipation even at high frequencies. This device is ideal for high speed transfer of clock or data.

The FIN1027 or FIN1027A can be paired with its companion receiver, the FIN1028, or with any other LVDS receiver.

Features

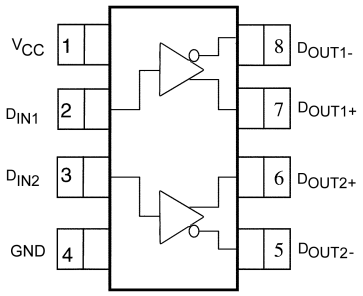
- Greater than 600Mbs data rate
- 3.3V power supply operation
- 0.5ns maximum differential pulse skew
- 1.5ns maximum propagation delay
- Low power dissipation
- Power-Off protection
- Meets or exceeds the TIA/EIA-644 LVDS standard
- Flow-through pinout simplifies PCB layout
- 8-Lead SOIC, US8, and 8-terminal MLP packages save space

Ordering Code:

Order Number	Package Number	Package Description
FIN1027M	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TUBE]
FIN1027MX	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TAPE and REEL]
FIN1027K8X	MAB08A	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide [TAPE and REEL]
FIN1027MPX (Preliminary)	MLP08C	8-Terminal Molded Leadless Package (MLP) Dual, JEDEC MO-229, 2mm Square [TAPE and REEL]
FIN1027AM	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TUBE]
FIN1027AMX	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TAPE and REEL]

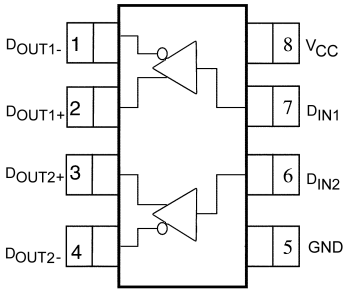
Connection Diagrams

Pin Assignments for SOIC
FIN1027



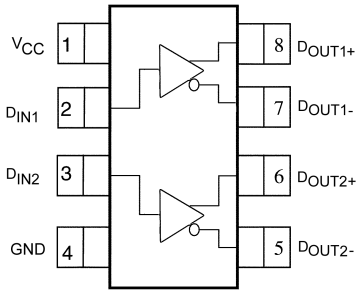
(Top View)

Pin Assignments for US8
for FIN1027



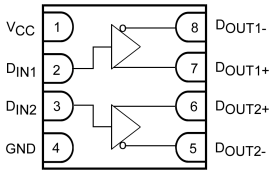
(Top View)

Pin Assignments for SOIC
FIN1027A



(Top View)

Terminal Assignments for MLP
FIN1027



(Top Through View)

Pin Descriptions

Pin Name	Description
D_{IN1}, D_{IN2}	LVTTL Data Inputs
D_{OUT1+}, D_{OUT2+}	Non-inverting Driver Outputs
D_{OUT1-}, D_{OUT2-}	Inverting Driver Outputs
V_{CC}	Power Supply
GND	Ground

Function Table

Input	Outputs	
D_{IN}	**D_{OUT+}**	**D_{OUT-}**
L	L	H
H	H	L
OPEN	L	H

H = HIGH Logic Level
L = LOW Logic Level
X = Don't Care

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	−0.5V to +4.6V
DC Input Voltage (D_{IN})	−0.5V to +6.0V
DC Output Voltage (D_{OUT})	−0.5V to +4.7V
Driver Short Circuit Current (I_{OSD})	Continuous
Storage Temperature Range (T_{STG})	−65°C to +150°C
Max Junction Temperature (T_J)	150°C
Lead Temperature (T_L)	
(Soldering, 10 seconds)	260°C
ESD (Human Body Model)	≥ 6500V
ESD (Machine Model)	≥ 400V

Recommended Operating Conditions

Supply Voltage (V_{CC})	3.0V to 3.6V
Input Voltage (V_{IN})	0 to V_{CC}
Operating Temperature (T_A)	−40°C to +85°C

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

DC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 2)	Max	Units
V_{OD}	Output Differential Voltage	R_L = 100 Ω, See Figure 1	250	350	450	mV
ΔV_{OD}	V_{OD} Magnitude Change from Differential LOW-to-HIGH				25	mV
V_{OS}	Offset Voltage		1.125	1.25	1.375	V
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH				25	mV
I_{OFF}	Power Off Output Current	V_{CC} = 0V, V_{OUT} = 0V or 3.6V			±20	µA
I_{OS}	Short Circuit Output Current	V_{OUT} = 0V			−8	mA
		V_{OD} = 0V			±8	
V_{IH}	Input HIGH Voltage		2.0		V_{CC}	V
V_{IL}	Input LOW Voltage		GND		0.8	V
I_{IN}	Input Current	V_{IN} = 0V or V_{CC}			±20	µA
$I_{I(OFF)}$	Power-Off Input Current	V_{CC} = 0V, V_{IN} = 0V or 3.6V			±20	µA
V_{IK}	Input Clamp Voltage	I_{IK} = −18 mA	−1.5			V
I_{CC}	Power Supply Current	No Load, V_{IN} = 0V or V_{CC}			12.5	mA
		R_L = 100 Ω, V_{IN} = 0V or V_{CC}			17.0	mA
C_{IN}	Input Capacitance			4		pF
C_{OUT}	Output Capacitance			6		pF

Note 2: All typical values are at T_A = 25°C and with V_{CC} = 3.3V.

AC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 3)	Max	Units
t_{PLHD}	Differential Propagation Delay LOW-to-HIGH	R_L = 100 Ω, C_L = 10pF, See Figure 2 and Figure 3	0.5		1.5	ns
t_{PHLD}	Differential Propagation Delay HIGH-to-LOW		0.5		1.5	ns
t_{TLHD}	Differential Output Rise Time (20% to 80%)		0.4		1.0	ns
t_{THLD}	Differential Output Fall Time (80% to 20%)		0.4		1.0	ns
$t_{SK(P)}$	Pulse Skew $\|t_{PLH} - t_{PHL}\|$				0.5	ns
$t_{SK(LH)}$, $t_{SK(HL)}$	Channel-to-Channel Skew (Note 4)				0.3	ns
$t_{SK(PP)}$	Part-to-Part Skew (Note 5)				1.0	ns

Note 3: All typical values are at T_A = 25°C and with V_{CC} = 3.3V.

Note 4: $t_{SK(LH)}$, $t_{SK(HL)}$ is the skew between specified outputs of a single device when the outputs have identical loads and are switching in the same direction.

Note 5: $t_{SK(PP)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

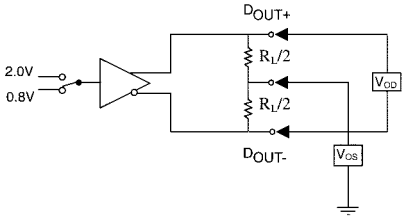
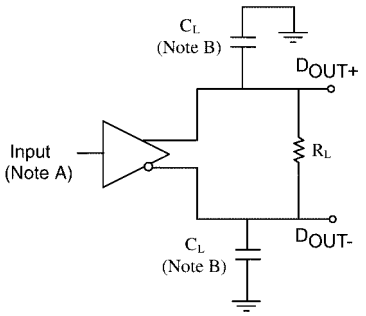


FIGURE 1. Differential Driver DC Test Circuit



Note A: All input pulses have frequency = 10 MHz, t_R or t_F = 2 ns

Note B: C_L includes all probe and fixture capacitances

FIGURE 2. Differential Driver Propagation Delay and Transition Time Test Circuit

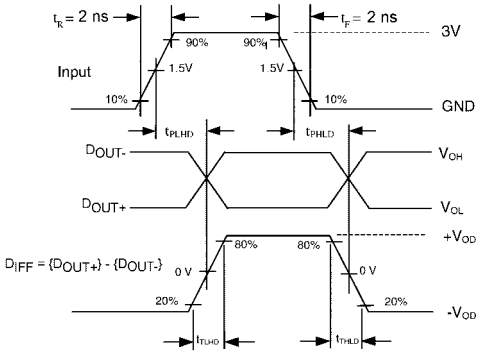


FIGURE 3. AC Waveforms

DC / AC Typical Performance Curves

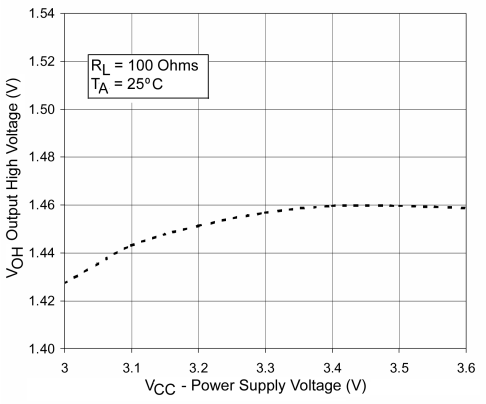


FIGURE 4. Output High Voltage vs. Power Supply Voltage

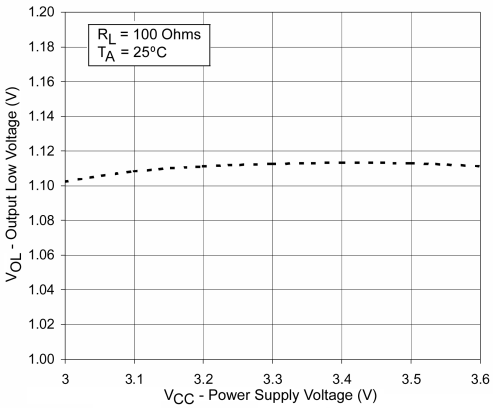


FIGURE 5. Output Low Voltage vs. Power Supply Voltage

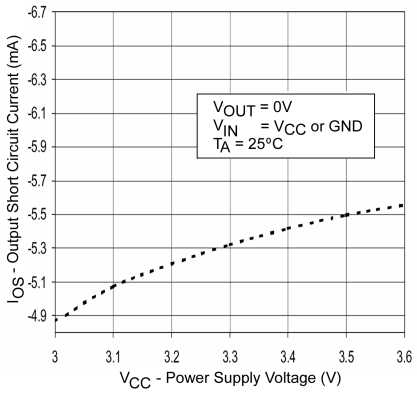


FIGURE 6. Output Short Circuit Current vs. Power Supply Voltage

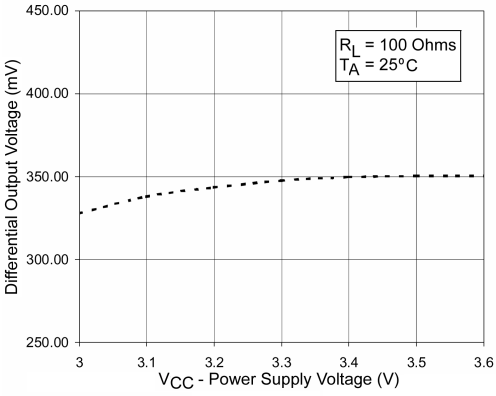


FIGURE 7. Differential Output Voltage vs. Power Supply Voltage

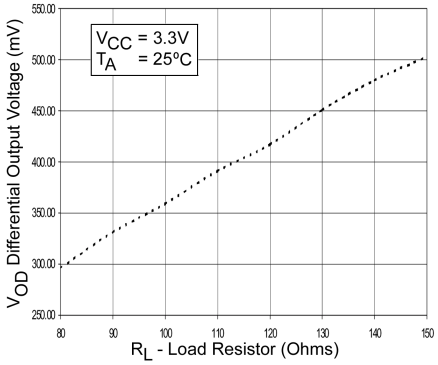


FIGURE 8. Differential Output Voltage vs. Load Resistor

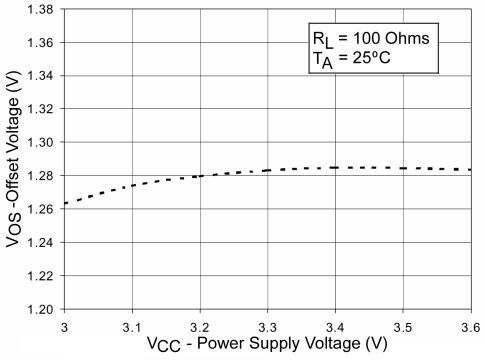


FIGURE 9. Offset Voltage vs. Power Supply Voltage

DC / AC Typical Performance Curves (Continued)

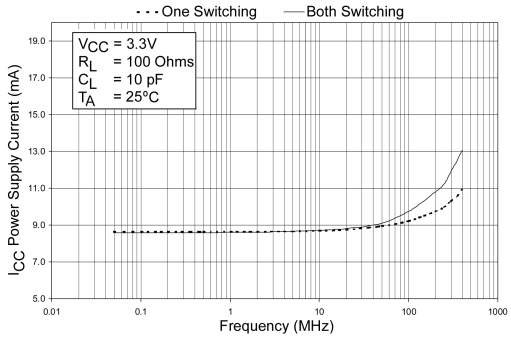


FIGURE 10. Power Supply Current vs. Frequency

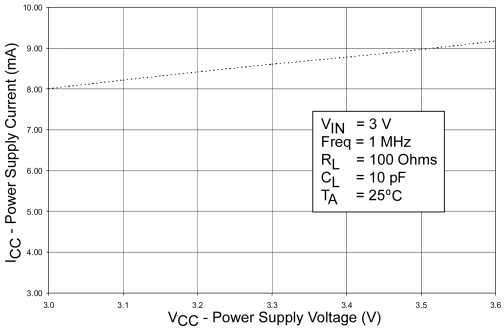


FIGURE 11. Power Supply Current vs. Power Supply Voltage

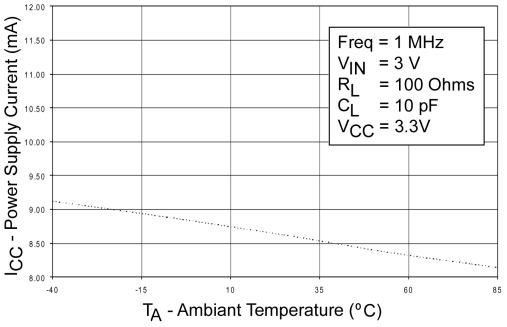


FIGURE 12. Power Supply Current vs. Ambient Temperature

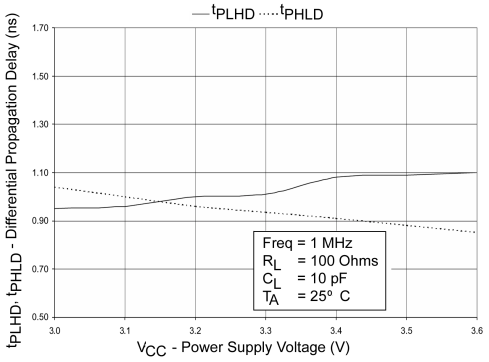


FIGURE 13. Differential Propagation Delay vs. Power Supply

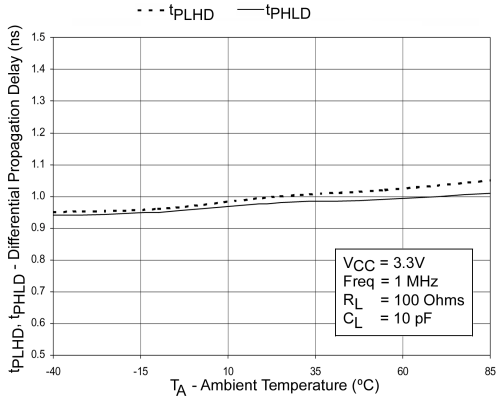


FIGURE 14. Differential Propagation Delay vs. Ambient Temperature

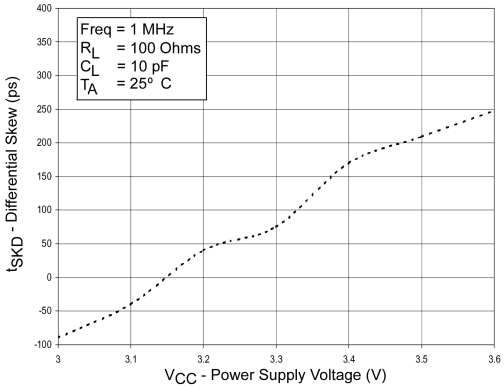


FIGURE 15. Differential Skew (t_{PLH} - t_{PHL}) vs. Power Supply

DC / AC Typical Performance Curves (Continued)

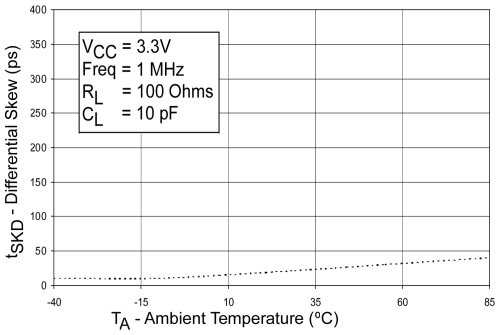


FIGURE 16. Differential Pulse Skew (t_{PLH} - t_{PHL}) vs. Ambient Temperature

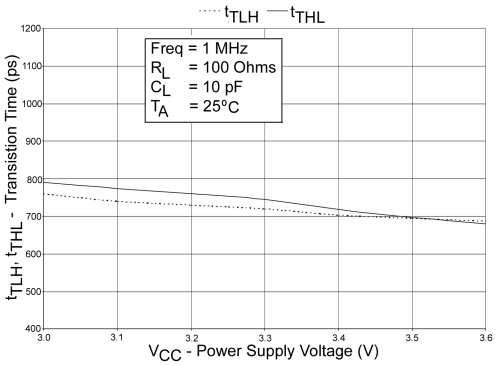


FIGURE 17. Transition Time vs. Power Supply Voltage

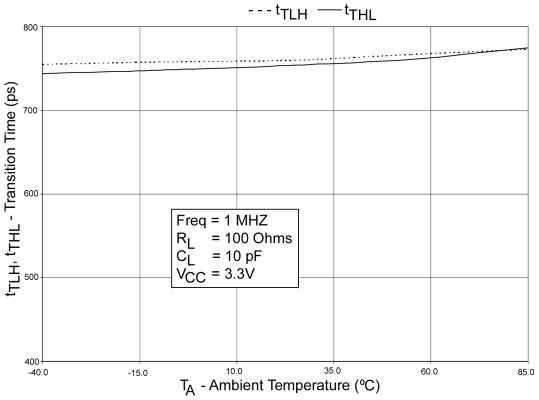


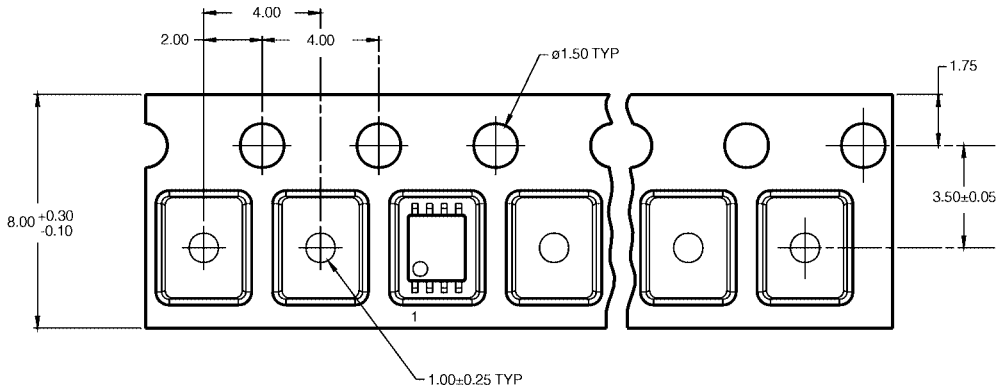
FIGURE 18. Transition Time vs. Ambient Temperature

Tape and Reel Specification

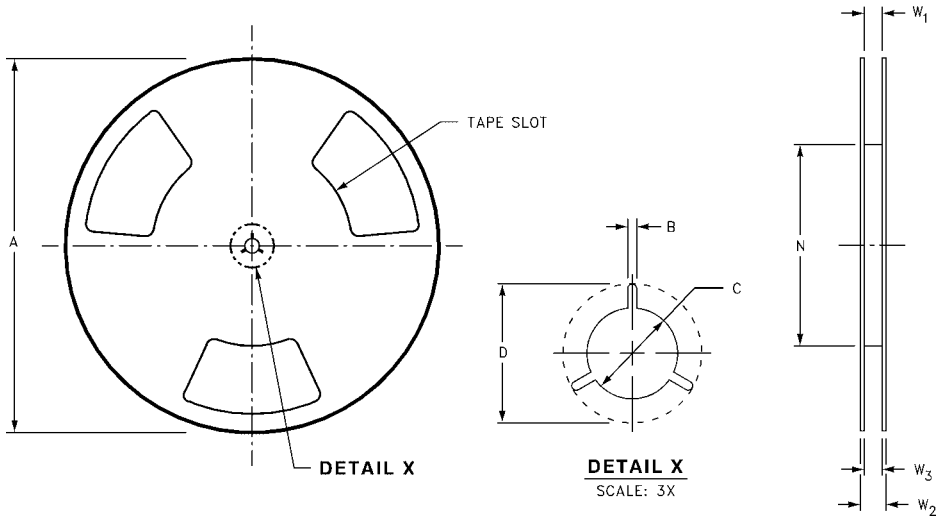
TAPE FORMAT for US8

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
K8X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	250	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

TAPE DIMENSIONS inches (millimeters)



REEL DIMENSIONS inches (millimeters)



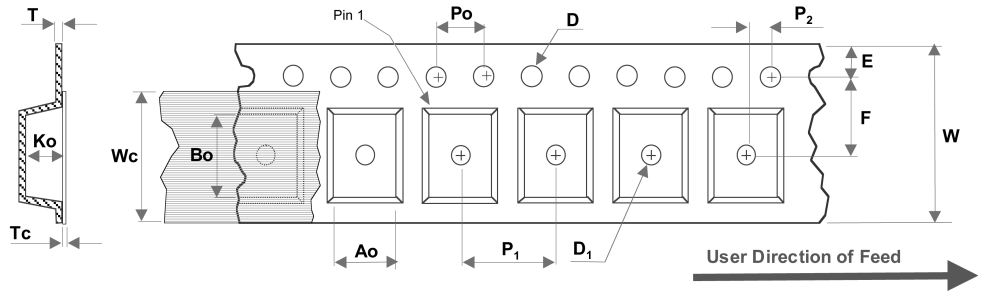
Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/–0.000 (8.40 + 1.50/–0.00)	0.567 (14.40)	W1 + 0.078/–0.039 (W1 + 2.00/–1.00)

Tape and Reel Specification

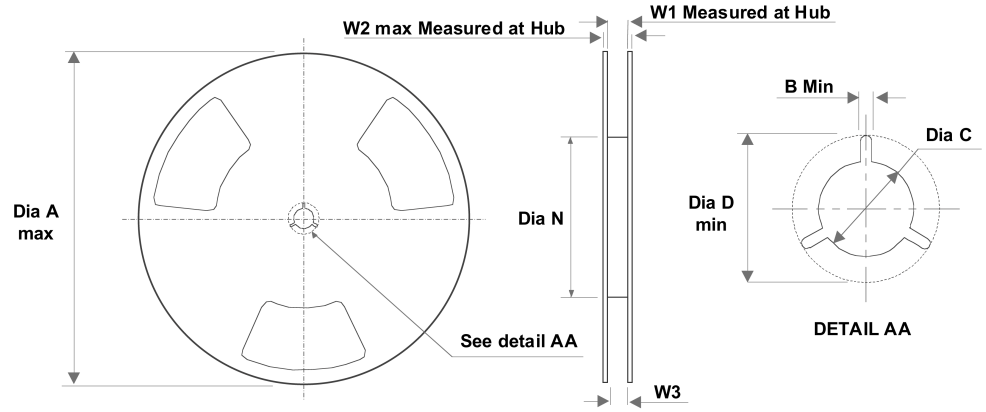
TAPE FORMAT for MLP

Package	Ao ±0.10	Bo ±0.10	D ±0.05	D_1 Min	E ±0.1	F ±0.1	Ko ±0.1	P_1 TYP	Po TYP	P_2 ±0/05	T TYP	T_C ±0.005	W ±0.3	Wc TYP
2 x 2	2.30	2.30	1.55	1.0	1.75	3.5	1.0	8.0	4.0	2.0	0.3	0.06	8.0	5.3

MLP Embossed Tape Dimensions (Dimensions are in millimeters)

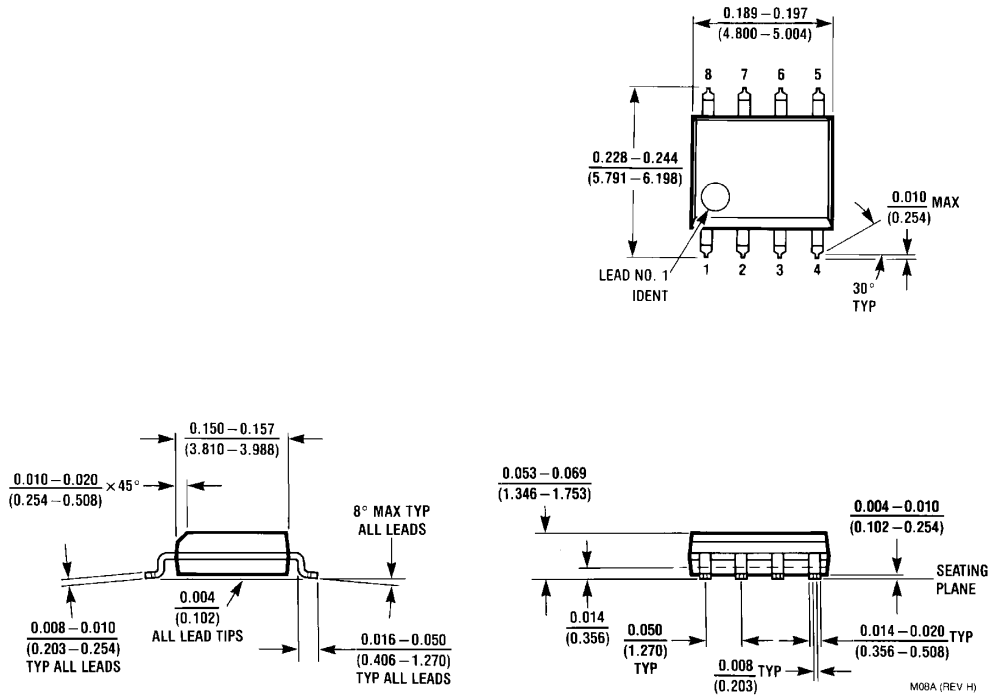


REEL DIMENSIONS (millimeters)



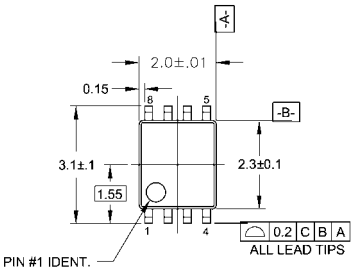
Tape Width	Dia A Max	Dim B Min	Dia C +0.5/–0.2	Dia D Min	Dim N Min	Dim W1 +2/–0	Dim W2 Max	Dim W3 (LSL - USL)
8 mm	330	1.5	13	20.2	178	8.4	14.4	7.9 ~ 10.4

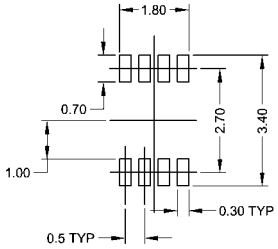
Physical Dimensions inches (millimeters) unless otherwise noted



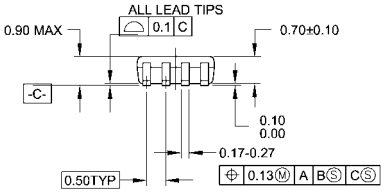
8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M08A

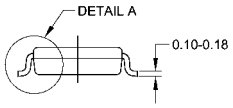
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

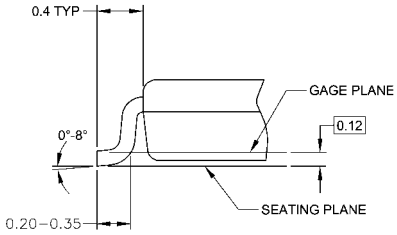




LAND PATTERN RECOMMENDATION







DETAIL A

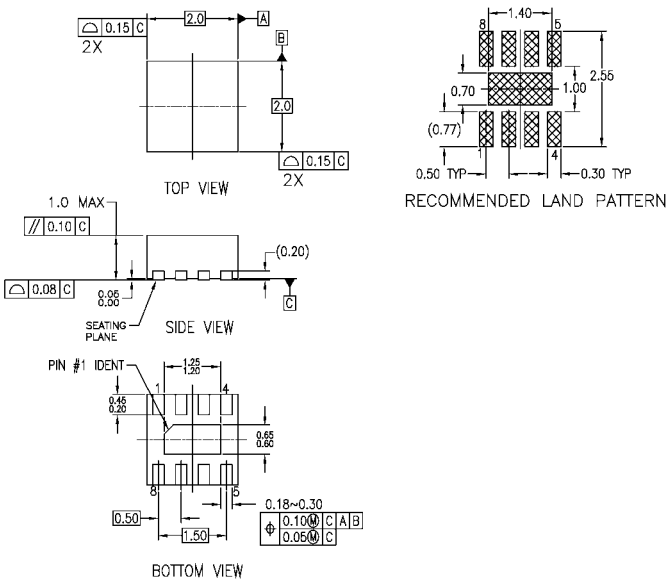
NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-187
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MAB08AREVC

8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide
Package Number MAB08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VCCD-3, DATED 11/2001
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP08CrevB

8-Terminal Molded Leadless Package (MLP) Dual, JEDEC MO-229, 2mm Square
Package Number MLP08C
(Preliminary)